What is claimed is:

1. A porous insulating film comprising a highly heat resistant resin film having a fine porous structure with a mean pore size of 0.01-5 μm in at least the center of the film, and having a porosity of 15-80%.

- 2. A porous insulating film according to claim 1, wherein the mean pore size is $0.05-1~\mu m$.
- 3. A porous insulating film according to claim 1, wherein the porosity is 30-80%.

A porous insulating film according to claim 1, which has a thickness of 5-150 μm .

5. A porous insulating film according to claim 1, wherein the fine porous structure consists of fine continuous pores.

6. A porous insulating film according to claim 1, which is fabricated by a film casting method.

- 7. A porous insulating film according to claim 1, wherein the dielectric constant is no greater than 2.5.
- 8. A porbus insulating film according to claim 1, wherein the highly heat resistant resin film is a polyimide film.
- 9. A polous insulating film according to claim 1, wherein the porous structure has fine continuous pores reaching to both surfaces.
- 10. A porous insulating film according to claim 9, which has a porosity of 30-80%, a maximum pore size of no greater than 10 μ m, a film thickness of 5-100 μ m, a resistance to passage of air of from 30 sec/100 cc to 2000 sec/100 cc, a heat resistance temperature of 200°C or above and a heat shrinkage of no greater than ±1%.
- 11. A porous insulating film according to claim 1, wherein the porous structure has a dense layer on both surfaces of the tilm.
- 12. A laminate prepared by forming a heat resistant adhesive layer on one or both sides of a porous insulating film according to claim 1.

15

70 Da

25

/ 30

35

5

- 13. A laminate prepared by laminating a conductive metal layer for an electronic circuit on one or both sides of a porous insulating film according to claim 1, either directly or via a heat resistant adhesive layer.
- 14. A laminate prepared by laminating an inorganic or metal substrate onto one side of a porous insulating film according to claim 1 and a conductive metal layer onto the other side, each via a heat resistant adhesive layer.

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